



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSL305SPE H6327	Issued	18. August 2021
MA#	MA001241632		
Package	PG-TSOP6-6-6	Weight*	13.61 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.007	0.05		517	
	noble metal	gold	7440-57-5	0.027	0.20		2003	
	inorganic material	silicon	7440-21-3	0.416	3.06	3.31	30558	33078
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		434	
	non noble metal	chromium	7440-47-3	0.018	0.13		1302	
	non noble metal	copper	7440-50-8	5.882	43.22	43.40	432177	434000
wire	non noble metal	copper	7440-50-8	0.078	0.57	0.57	5715	5715
encapsulation	organic material	carbon black	1333-86-4	0.067	0.49		4923	
	plastics	epoxy resin	-	1.441	10.58		105843	
	inorganic material	silicondioxide	60676-86-0	5.193	38.15	49.22	381526	492292
leadfinish	non noble metal	tin	7440-31-5	0.299	2.20	2.20	21962	21962
plating	noble metal	silver	7440-22-4	0.176	1.30	1.30	12953	12953
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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